IN THE CLAIMS:

Claims 6, 7, 10, 15, and 22 have been amended herein. All of the pending claims 1 through 22 are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

1. (Previously presented) An interposer for use in a semiconductor device package, comprising:
a substrate;
at least one first contact pad on the substrate, the at least one first contact pad being located proximate at least one opening extending through the substrate;
at least one second contact pad on the substrate;
at least one electrical trace communicating at a first end thereof with the at least one first contact pad and at a second end thereof with the at least one second contact pad; and
at least one dam located on the substrate so as to laterally surround at least a portion of the at least one opening and comprising a projection including a plurality of adjacent, mutually adhered regions comprising the same material.

2. (Previously presented) The interposer of claim 1, wherein the at least one dam completely laterally surrounds the at least one opening.

3. (Previously presented) The interposer of claim 1, wherein the at least one first contact pad is located on the same surface of the substrate as the at least one dam.

4. (Previously presented) The interposer of claim 3, wherein the at least one dam at least partially laterally surrounds the at least one first contact pad.

5. (Previously presented) The interposer of claim 3, wherein the at least one dam completely laterally surrounds the at least one first contact pad.

6. (Currently amended) The interposer of claim 1, wherein the at least one ~~upwardly protruding~~ dam at least partially laterally surrounds the at least one second contact pad.

7. (Currently amended) The interposer of claim 6, wherein the at least one ~~upwardly protruding~~ dam completely laterally surrounds the at least one second contact pad.

8. (Previously presented) The interposer of claim 1, wherein each region of the plurality of adjacent, mutually adhered regions of the at least one dam comprises photopolymer.

9. (Previously presented) The interposer of claim 1, wherein the plurality of adjacent, mutually adhered regions of the at least one dam comprise a plurality of superimposed, contiguous, mutually adhered layers.

10. (Currently amended) The interposer of claim 1, further comprising at least one sealing element on an opposite surface of the substrate ~~from the~~ from a surface by which the at least one dam is carried, the at least one sealing element substantially laterally surrounding the at least one opening.

11. (Previously presented) The interposer of claim 10, wherein the at least one sealing element at least partially comprises at least semisolid photopolymer.

12. (Previously presented) The interposer of claim 11, wherein the at least one sealing element further comprises an adhesive film.

13. (Previously presented) The interposer of claim 11, wherein the at least semisolid photopolymer is located adjacent at least a portion of an outer periphery of the substrate.

14. (Previously presented) The interposer of claim 11, wherein the at least semisolid photopolymer is located adjacent at least a portion of a periphery of the at least one opening.

15. (Currently amended) The interposer of claim 1, wherein the at least one second contact pad is located between the at least one ~~upwardly protruding~~ dam and an outer periphery of the substrate.

16. (Previously presented) The interposer of claim 1, further comprising at least one conductive structure protruding from the at least one second contact pad.

17. (Previously presented) The interposer of claim 16, wherein the at least one conductive structure comprises metal, conductive elastomer, or conductor-filled epoxy.

18. (Previously presented) The interposer of claim 16, wherein the at least one conductive structure is located between the at least one dam and an outer periphery of the substrate.

19. (Previously presented) The interposer of claim 1, wherein the at least one dam is configured to laterally confine a quantity of nonconductive encapsulant over the at least one opening.

20. (Previously presented) The interposer of claim 19, wherein the nonconductive encapsulant has a substantially planar surface.

21. (Previously presented) The interposer of claim 19, further comprising at least one conductive structure protruding through the nonconductive encapsulant.

22. (Currently amended) An interposer for use in a semiconductor device package, comprising:

a substrate;

at least one first contact pad on the substrate, the at least one first contact pad being located proximate at least one opening extending through the substrate;

at least one second contact pad on the substrate;

at least one electrical trace communicating at a first end thereof with the at least one first contact pad and at a second end thereof with the at least one second contact pad; and

at least one dam positioned on the substrate so as to laterally surround at least a portion of the at least one opening, with at least a portion ~~of the~~ of a surface of the substrate being exposed between the at least one dam ~~and the~~ and an outer periphery of the substrate, and the at least one dam including a plurality of adjacent, mutually adhered regions comprising the same material.